| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 7 | 45464 | (interlayer inter-layer) near2 (insulat$3 dielectric) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/19 17:29 |
| 8 | 4443653 | via hole plug stud | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/19 17:30 |
| 9 | 490420 | pad | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/19 17:30 |
| 10 | 5025 | ((interlayer inter-layer) near2 (insulat$3 dielectric)) and (via hole plug stud) and pad | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/19 17:31 |
| 11 | 15433 | bump near2 (electrode conduct$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/19 17:32 |
| 12 | 234 | (((interlayer inter-layer) near2 (insulat$3 dielectric)) and (via hole plug stud) and pad) and (bump near2 (electrode conduct$3)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/19 17:32 |

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